

# Thales Group Competence Center for Printed Circuit Boards

The Thales Group Competence Center Printed Circuit Boards is a low-volume supplier of high performance and high reliability complex and advanced printed circuit boards for mission critical systems.

The printed circuit board facility in Hengelo has evolved since 1969 as an internal manufacturing department within Thales Netherlands, supporting prototyping, new product introduction and technology developments for radar frontend systems. In 2012 it was appointed Thales Group Competence Center Printed Circuit Boards (GCC PCB) offering a wide range of capabilities specially tailored to the Thales Group needs with emphasis on advanced and complex RF and mixed signal printed circuit boards. Production is performed primarily for a customer base in:

- Avionics
- Space
- Defence
- High Rel Industrial applications

With respect to quality control and assurance the centre holds MIL 55110 and MIL 31032, ISO 14001 and ISO 9001 certifications and is a member of the IPC. Inspection is performed in compliance with IPC class 2 and 3 requirements. The Thales Group internal acceptance criteria: TRT 16 262 721 for rigid printed circuit boards and TRT 16 261 983 for microwave printed circuit boards are being implemented as part of the GCC activities. In-house reliability testing and environmental stress screening are available. Product categories and application areas include power modules, analogue boards, HDI, high speed digital multi layers, mixed signal boards, stripline flex and rigid structures, and antenna panels.

Rigid panels size up to 24x(36-48) inches and flexible layers up to a length of 10 m can be manufactured. A wide multilayer material experience ranging from FR4, PI, a large variety of RF materials (Rogers and teflons) and their combinations together with metal core materials like aluminium, BeO and AlSi and copper is present. The PCB center exhibits technical capabilities including laser direct imaging, advanced mechanical drilling and routing equipment in order to fulfil demanding registration requirements. The current lithography processes are upgraded towards state-of-the-art-fine-line capabilities. Interconnection techniques include UV/CO2 dual-source micro via laser drilling, via hole filling and over plating. Additional features like cavities, back drilling, embedded resistors and thermal management are also part of the technology portfolio. Advanced AOI, BBT testing and cross section analysis is used. Available surface finishes are HAL (PbSn), ENIG, ENEPIG, selective electrolytic PbSn, selective electrolytic Ni and hard- or soft Au and their possible combinations.

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